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ABSTRACT OF THE DISCLOSURE

An apparatus for increasing integrated circuit density includes, generally, a dual LOC semiconductor die, a first die attach frame mechanically back bonded to a die attach frame, a first offset lead frame, each having a first die attach frame on opposing sides thereof, and a second die in a cantilevered position relative to the first die. The lead fingers to corresponding bond pads are formed therebetween. The assembly is then mounted on a substrate. The stacked dual LOC semiconductor die is then electrically connected to the substrate.